



### 650V FIELD STOP IGBT IN ITO220AB

### Description

The DGTD65T15H2TF is produced using advanced Field Stop Trench IGBT Technology, which provides high-performance, excellent quality, and high ruggedness.

### **Features**

- High Ruggedness for Motor Control
- V<sub>CE(sat)</sub> Positive Temperature Coefficient
- Very Soft, Fast Recovery Anti-Parallel Diode
- Low EMI
- Maximum Junction Temperature +175°C
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Applications**

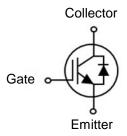
Motor Drive

### **Mechanical Data**

- Case: ITO220AB (Type MC)
- Case Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Terminals: Finish—Matte Tin Plated Leads.
   Solderable per MIL-STD-202, Method 208 (2)
- Weight: 1.9 grams (Approximate)



ITO220AB (Type MC)



Device Symbol

## **Ordering Information** (Note 4)

Product	Marking	Quantity		
DGTD65T15H2TF	DGTD65T15H2	1000 per Box in Tubes (Note 5)		

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.
- 5. 50 devices per tube.

## **Marking Information**



);; = Manufacturer's Marking
DGTD65T15H2 = Product Type Marking Code
YY = Year (ex: 18 = 2018)
LLLLL = Lot Code
WW = Week (01 to 53)



## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Collector-Emitter Voltage		V <sub>CE</sub>	650	V
DC Collector Current Limited by T	T <sub>C</sub> = +25°C		30	Α
DC Collector Current, Limited by T <sub>jmax</sub>	$T_C = +100^{\circ}C$	Ic	15	Α
Pulsed Collector Current, tp Limited by Tjmax		I <sub>Cpuls</sub>	60	Α
Diada Famuand Cumant Limited bu T	T <sub>C</sub> = +25°C		30	Α
Diode Forward Current Limited by T <sub>jmax</sub>	$T_C = +100^{\circ}C$	I <sub>F</sub>	15	Α
Diode Pulsed Current, tp Limited by Tjmax		I <sub>Fpuls</sub>	60	Α
Gate-Emitter Voltage		$V_{GE}$	±20	V
Short Circuit Withstand Time $V_{CC} \le 360V$ , $V_{GE} = 15V$ , $T_i = +150$ °C		t <sub>SC</sub>	5	μs

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

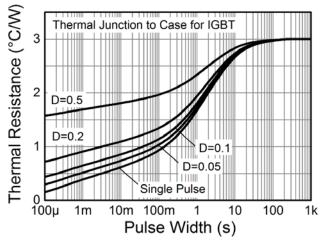
Characteristic	Symbol	Value	Unit	
Power Dissipation Linear Derating Factor (Note 7)  T <sub>C</sub> = +25°C	P <sub>D</sub>	48	W	
T <sub>C</sub> = +100°C		24		
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>OJA</sub>	62		
Thermal Resistance, Junction to Case for IBGT (Note 7)	R <sub>OJC</sub>	3.0	°C/W	
Thermal Resistance, Junction to Case for Diode (Note 7)	R <sub>OJC</sub>	5.0		
Operating Temperature	T <sub>i</sub>	-40 to +175	- °C	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150		

Note:

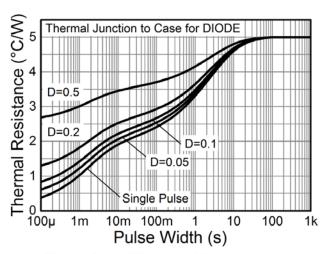
<sup>6.</sup> For a device mounted in a socket in still air conditions. Collector lead length 10mm. 7. For a device mounted on a Force Cooled Aluminium Heatsink 80x80x60mm.



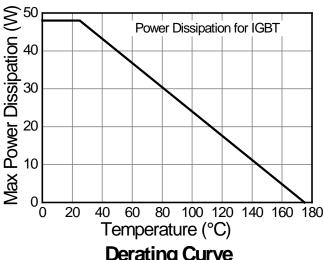
## Thermal Characteristics and Derating Information



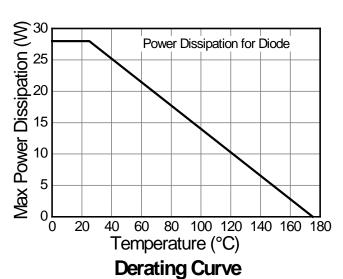
**Transient Thermal Impedance** 

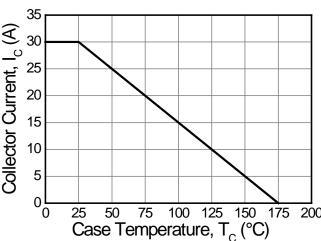


**Transient Thermal Impedance** 



**Derating Curve** 





Case Temperature-Collector Current



# Electrical Characteristics (@ $T_j = +25$ °C, unless otherwise specified.)

Parameter		Symbol	Min	Тур	Max	Unit	Condition	
STATIC CHARACTERISTICS					•			
Collector-Emitter Breakdown Voltage		BV <sub>CES</sub>	650	_	_	V	$I_C = 2mA$ , $V_{GE} = 0V$	
Collector-Emitter Saturation Voltage	$T_j = +25^{\circ}C$	j = +25°C		1.65	2.00	V	I <sub>C</sub> = 15A, V <sub>GE</sub> = 15V	
Collector-Entitler Saturation Voltage	$T_j = +175^{\circ}C$	V <sub>CE(sat)</sub>	_	1.90	_			
Diode Forward Voltage	$T_j = +25$ °C	$V_{F}$	_	1.85	2.30	V	V <sub>GF</sub> = 0V, I <sub>F</sub> = 15A	
blode i diward voltage	$T_j = +175^{\circ}C$	٧F		1.95	_	V	VGE = 0V, IF = 15A	
Gate-Emitter Threshold Voltage		$V_{GE(th)}$	4.5	5.5	6.5	V	$V_{CE} = V_{GE}$ , $I_C = 0.5 mA$	
		Ices		_	20	μA	$V_{CE} = 650V, V_{GE} = 0V,$	
Zero Gate Voltage Collector Current		ICES			20	μΛ	$T_j = +25$ °C	
Gate-Emitter Leakage Current		I <sub>GES</sub>	_	_	±100	nA	$V_{GE} = 20V, V_{CE} = 0V$	
DYNAMIC CHARACTERISTICS				1	1			
Total Gate Charge		$Q_{g}$	_	61	_		$V_{CE} = 520V, I_{C} = 15A,$	
Gate-Emitter Charge		$Q_{ge}$	_	11	_	nC	$V_{GE} = 020 V, I_{GE} = 10 V,$	
Gate-Collector Charge		$Q_{gc}$	_	35	_		VGL = 10V	
Input Capacitance		C <sub>ies</sub>	_	1129	_		V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz	
Reverse Transfer Capacitance		$C_{res}$	_	57	_	pF		
Output Capacitance		Coes	_	31	_		· ·····-	
SWITCHING CHARACTERISTICS				1	ı			
Turn-On Delay Time		t <sub>d(on)</sub>	_	19	_			
Rise Time		t <sub>r</sub>	_	27	_	ns	V <sub>GE</sub> = 15V, V <sub>CC</sub> = 400V,	
Turn-Off Delay Time		t <sub>d(off)</sub>	_	128	_		$I_{C} = 15A$ , $R_{G} = 10\Omega$ ,	
Fall Time		t <sub>f</sub>	_	32	_		Inductive Load,	
Turn-On Switching Energy		E <sub>on</sub>	_	270	_		T <sub>i</sub> = +25°C	
Turn-Off Switching Energy		E <sub>off</sub>		86	_	μJ	,	
Total Switching Energy		E <sub>ts</sub>		356	_			
Turn-On Delay Time		t <sub>d(on)</sub>	_	17	_		$V_{GE} = 15V, \ V_{CC} = 400V, \\ I_{C} = 15A, \ R_{G} = 10\Omega, \\ Inductive \ Load, \\ T_{j} = +175^{\circ}C$	
Rise Time		t <sub>r</sub>	_	29	_	ns		
Turn-Off Delay Time		t <sub>d(off)</sub>	_	150	_	113		
Fall Time		t <sub>f</sub>	_	130	_			
Turn-On Switching Energy		E <sub>on</sub>	_	342	_			
Turn-Off Switching Energy		E <sub>off</sub>	_	288	_	μJ		
Total Switching Energy		E <sub>ts</sub>		630	_			
Reverse Recovery Time		t <sub>rr</sub>		150		ns	1_ 1EA di=/dt 000A/:	
Reverse Recovery Current		Irr		5.2	_	$A$ $I_F = 15A$ , $di_F/dt = 200A/\mu s$ ,		
Reverse Recovery Charge		Q <sub>rr</sub>	_	390	_	nC	$T_j = +25^{\circ}C$	
Reverse Recovery Time		t <sub>rr</sub>	_	207	_	ns	1 45A di /dr 000A/:	
Reverse Recovery Current		I <sub>rr</sub>		6.1	— A I <sub>F</sub> = 15A, di <sub>F</sub> /dt = 200A/μ:		T <sub>F</sub> = 15A, dif/dt = 200A/μs, T <sub>i</sub> = +175°C	
Reverse Recovery Charge		$Q_{rr}$		631	_	nC 1 <sub>j</sub> = +175 C		



## Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

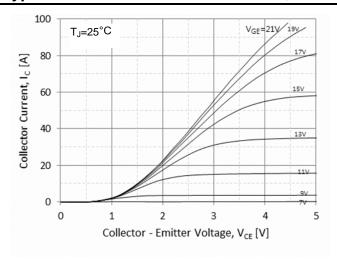


Fig.1 Typical Output Characteristics(T<sub>J</sub>=25°C)

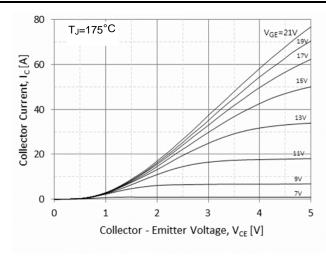


Fig.2 Typical Output Characteristics(T<sub>J</sub>=175°C)

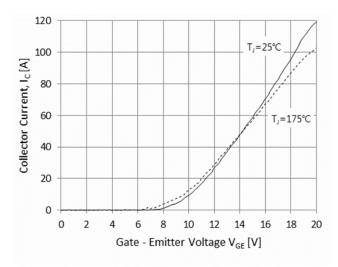


Fig.3 Typical Transfer Characteristics

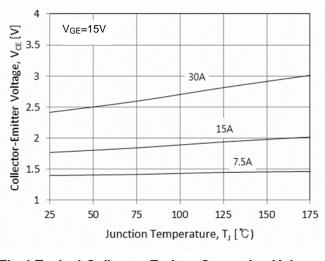


Fig.4 Typical Collector-Emitter Saturation Voltage
-Junction Temperature

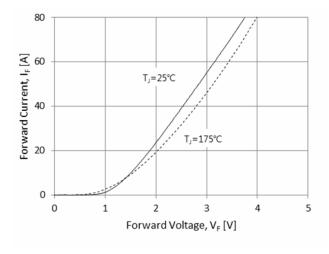


Fig.5 Diode Forward Characteristics

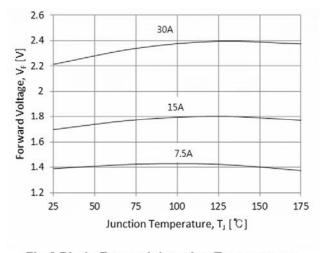
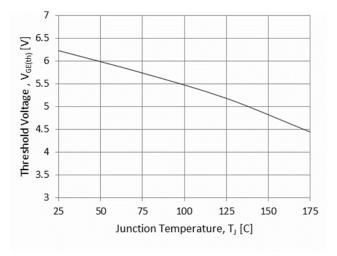


Fig.6 Diode Forward-Junction Temperature



## Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.) (continued)



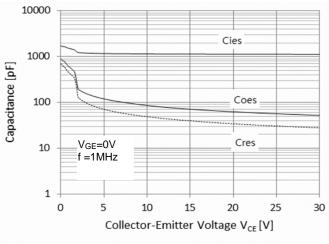


Fig.7 Threshold Voltage-Junction Temperature

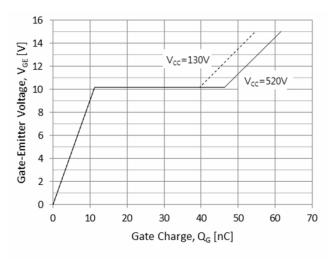


Fig.8 Typical Capacitance

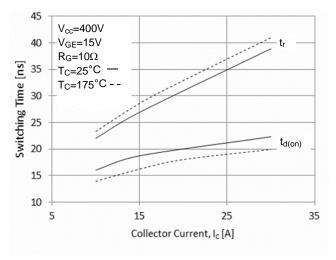


Fig.9 Typical Gate Charge

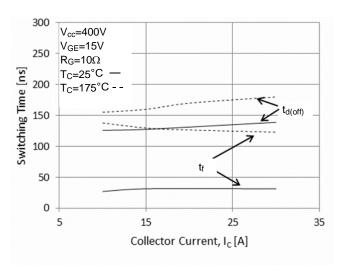


Fig.10 Typical Turn on-Collector Current

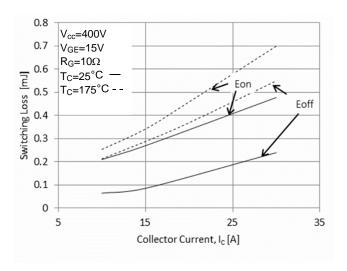
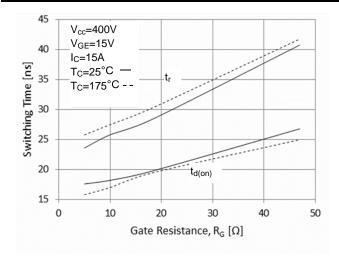


Fig.11 Typical Turn off-Collector Current

Fig.12 Switching Loss-Collector Current



## Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.) (cont.)



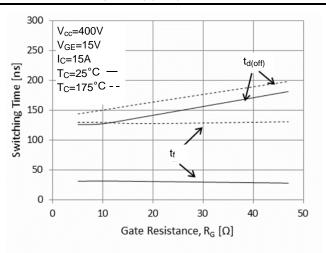


Fig.13 Turn on Characteristics-Gate Resistance

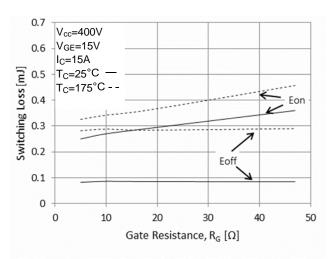


Fig.14 Turn off Characteristics-Gate Resistance

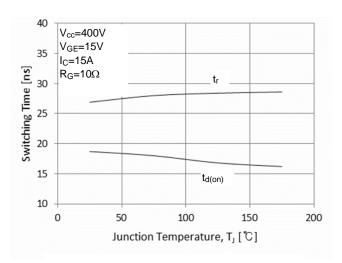


Fig.15 Switching Loss-Gate Resistance

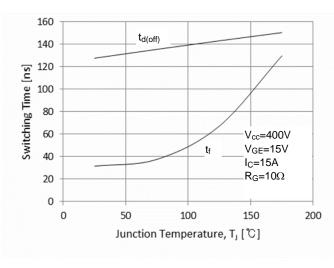


Fig.16 Turn on Characteristics-Junction
Temperature

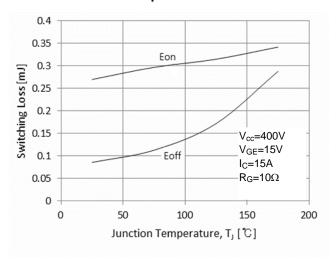


Fig.17 Turn off Characteristics-Junction Temperature

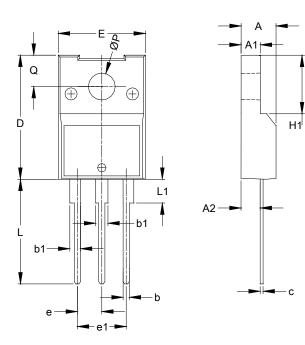
Fig.18 Switching Loss-Junction Temperature



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### ITO220AB (Type MC)



ITO220AB (Type MC)						
Dim	Min	Max	Тур			
Α	4.30	4.80	_			
<b>A</b> 1	2.50	3.10	_			
A2	2.30	2.90	_			
b	0.50	1.00				
b1	0.95	1.70	_			
С	0.40	0.80	_			
D	14.50	16.40				
H1	6.20	7.20	_			
Е	9.60	10.40				
е			2.54			
e1			5.08			
L	12.20	14.20	_			
L1	2.90	4.70	_			
Р	3.00	3.40	_			
Ø	2.40	3.50	_			
All Dimensions in mm						

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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